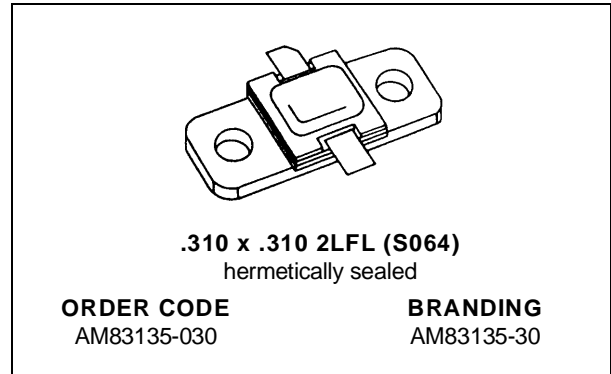


## RF & MICROWAVE TRANSISTORS S-BAND RADAR APPLICATIONS

PRELIMINARY DATA

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- LOW THERMAL RESISTANCE
- INPUT/OUTPUT MATCHING
- OVERLAY GEOMETRY
- METAL/CERAMIC HERMETIC PACKAGE
- $P_{OUT} = 30$  W MIN. WITH 5.5 dB GAIN

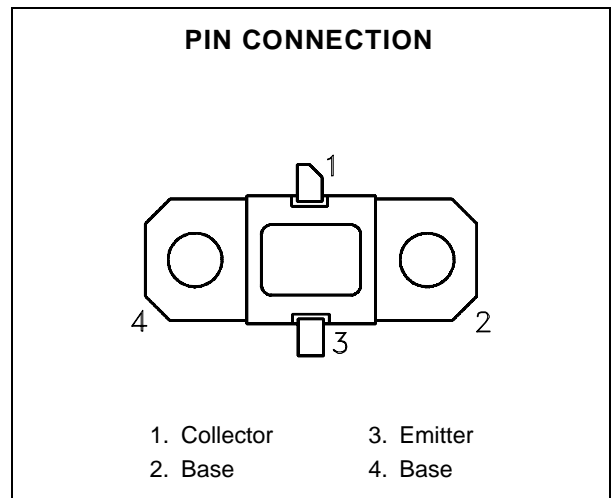


### DESCRIPTION

The AM83135-030 device is a high power silicon bipolar NPN transistor specifically designed for S-Band radar pulsed output and driver applications.

This device is characterized at 100 $\mu$ sec pulse width and 10% duty cycle, but is capable of operation over a range of pulse widths, duty cycles, and temperatures, and withstand a 3:1 output VSWR with a + 1 dB input overdrive. Low RF thermal resistance, refractory/gold metallization, and computerized automatic wire bonding techniques ensure high reliability and product consistency (including phase characteristics).

The AM83135-030 is supplied in the IMPAC™ Hermetic Metal/Ceramic package with internal Input/Output impedance matching circuitry, and is intended for military and other high reliability applications.



### ABSOLUTE MAXIMUM RATINGS ( $T_{case} = 25^{\circ}C$ )

Symbol	Parameter	Value	Unit
$P_{DISS}$	Power Dissipation* ( $T_C \leq 50^{\circ}C$ )	133	W
$I_C$	Device Current*	6.0	A
$V_{CC}$	Collector-Supply Voltage*	46	V
$T_J$	Junction Temperature (Pulsed RF Operation)	250	$^{\circ}C$
$T_{STG}$	Storage Temperature	- 65 to +200	$^{\circ}C$

### THERMAL DATA

$R_{TH(j-c)}$	Junction-Case Thermal Resistance*	1.5	$^{\circ}C/W$
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\*Applies only to rated RF amplifier operation

# AM83135-030

## ELECTRICAL SPECIFICATIONS (T<sub>case</sub> = 25°C)

### STATIC

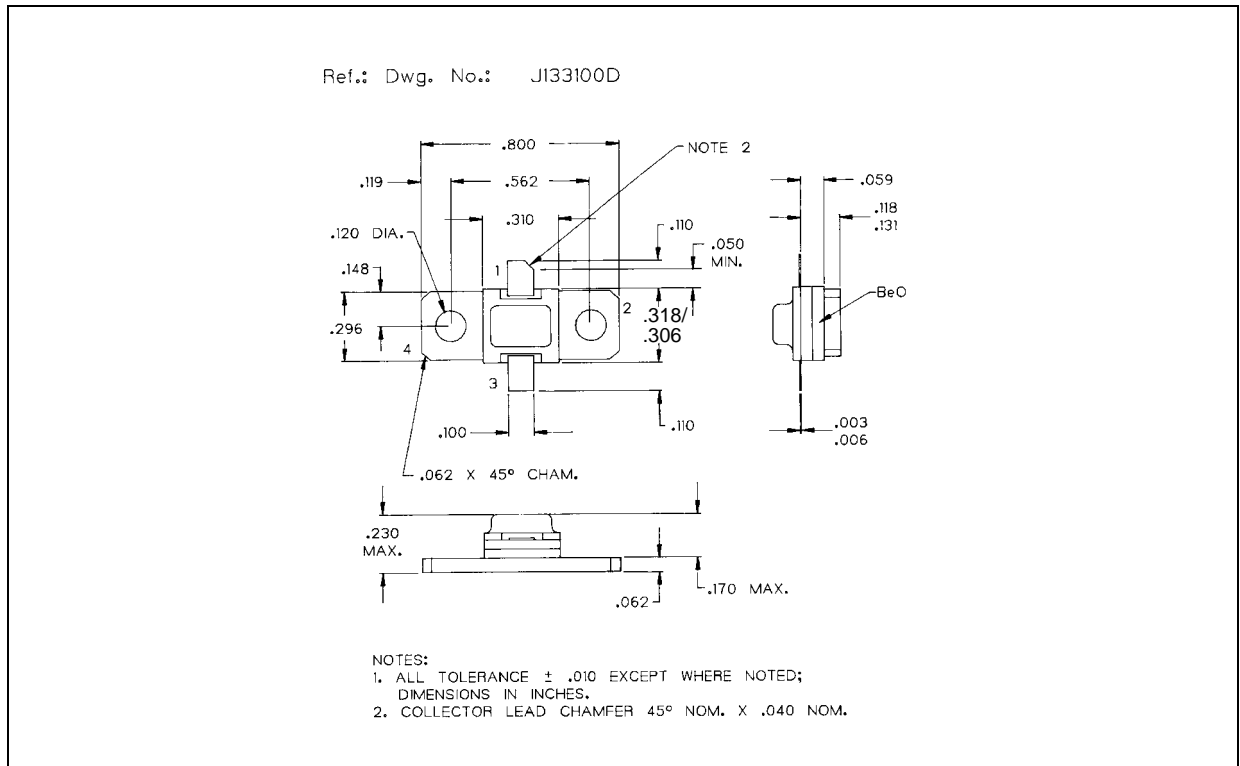
Symbol	Test Conditions		Value			Unit
			Min.	Typ.	Max.	
BV <sub>CBO</sub>	I <sub>C</sub> = 20mA	I <sub>E</sub> = 0mA	55	—	—	V
BV <sub>EBO</sub>	I <sub>E</sub> = 4mA	I <sub>C</sub> = 0mA	3.5	—	—	V
BV <sub>CER</sub>	I <sub>C</sub> = 20mA	R <sub>BE</sub> = 10Ω	55	—	—	V
I <sub>CES</sub>	V <sub>BE</sub> = 0V	V <sub>CE</sub> = 40V	—	—	15	mA
h <sub>FE</sub>	V <sub>CE</sub> = 5V	I <sub>C</sub> = 2A	30	—	300	—

### DYNAMIC

Symbol	Test Conditions			Value			Unit
				Min.	Typ.	Max.	
P <sub>OUT</sub>	f = 3.1 — 3.5GHz	P <sub>IN</sub> = 8.5W	V <sub>CC</sub> = 40V	30	—	—	W
η <sub>c</sub>	f = 3.1 — 3.5GHz	P <sub>IN</sub> = 8.5W	V <sub>CC</sub> = 40V	30	—	—	%
G <sub>P</sub>	f = 3.1 — 3.5GHz	P <sub>IN</sub> = 8.5W	V <sub>CC</sub> = 40V	5.5	—	—	dB

Note: Pulse Width = 100μSec  
Duty Cycle = 10%

## PACKAGE MECHANICAL DATA



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